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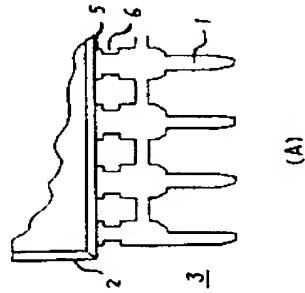
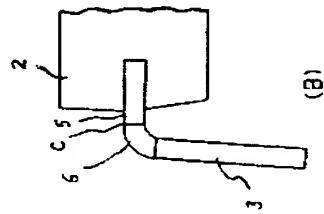
APPLICATION DATE : 14-01-86  
APPLICATION NUMBER : 61004134

APPLICANT : TOSHIBA CORP;

INVENTOR : KOMAI SEIICHI;

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TITLE : SEMICONDUCTOR DEVICE



ABSTRACT : PURPOSE: To prevent the intrusion of a harmful matter from a clearance with a molding resin generated in a bend section for lead, and to lengthen a lifetime by making the size of the bend section for the lead thinner than that of a lead in a resin-mold root section.

CONSTITUTION: The size of bend sections 6 for a lead 3 is made thinner than that of resin-mold root sections 5. The width of the bending sections 6 is made narrower than that of the lead in the root 5 sections to a resin mold body 2 of the lead 3 by a value such as approximately 15~25%. The bending sections 6 are positioned where separate by 0.05~0.1mm from the edges of the resin mold body 2. Consequently, since thinning sections are bent comparatively easily when executing a bending process for the lead, force is not applied to the resin mold body 2, and the lead 3 is not bent from the inside of the resin mold body 2. Accordingly, peeling sections by the bending of the lead are not generated, conventional harmful matters do not intrude, a lifetime is lengthened, and the holding period of the performance of a semiconductor element can be prolonged.

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